LMV1090 Dual Input, Far Field Noise Suppression Microphone Amplifier

Check for Samples: LMV1090

FEATURES

- **No Loss of Voice Intelligibility**
- **No Added Processing Delay**
- **Low Power Consumption**
- **Differential Outputs**
- **Excellent RF Immunity**
- **Adjustable 12 - 54dB Gain**
- **Shutdown Function**
- **Space-Saving 16–Bump DSBGA Package**

APPLICATIONS

- **Mobile Headset**
- **Mobile and Handheld Two-Way Radios**
- **Bluetooth and Other Powered Headsets**
- **Hand-held Voice Microphones**
- **Cell Phones**

KEY SPECIFICATIONS

- **Far Field Noise Suppression Electrical ($FFNS_E$ at f = 1kHz): 34dB (typ)**
- **SNRIE 26dB (typ)**
- **Supply Current: 600µA (typ)**
- **Standby Current 0.1µA (typ)**
- **Signal-to-Noise Ratio (Voice band): 65dB (typ)**
- **Total Harmonic Distortion + Noise: 0.1% (typ)**
- **PSRR (217Hz): 99dB (typ)**

DESCRIPTION

The LMV1090 is a fully analog dual differential input, differential output, microphone array amplifier designed to reduce background acoustic noise, while delivering superb speech clarity in voice communication applications.

The LMV1090 preserves near-field voice signals within 4cm of the microphones while rejecting far-field acoustic noise greater than 50cm from the microphones. Up to 20dB of far-field rejection is possible in a properly configured and using ±0.5dB matched microphones.

Part of the PowerWise ™ family of energy efficient solutions, the LMV1090 consumes only 600µA of supply current providing superior performance over DSP solutions consuming greater than ten times the power.

The dual microphone inputs and the processed signal output are differential to provide excellent noise immunity. The microphones are biased with an internal low-noise bias supply.

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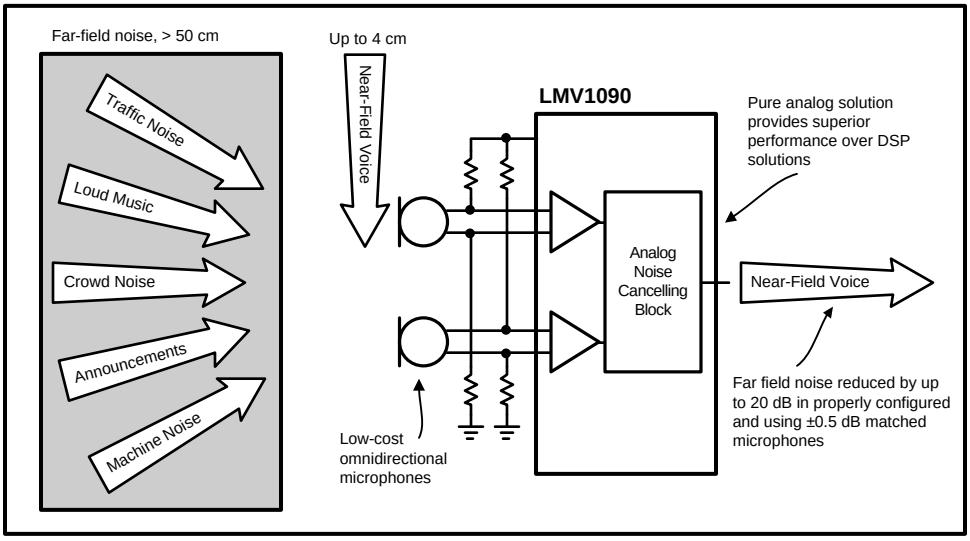
System Diagram



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Typical Application

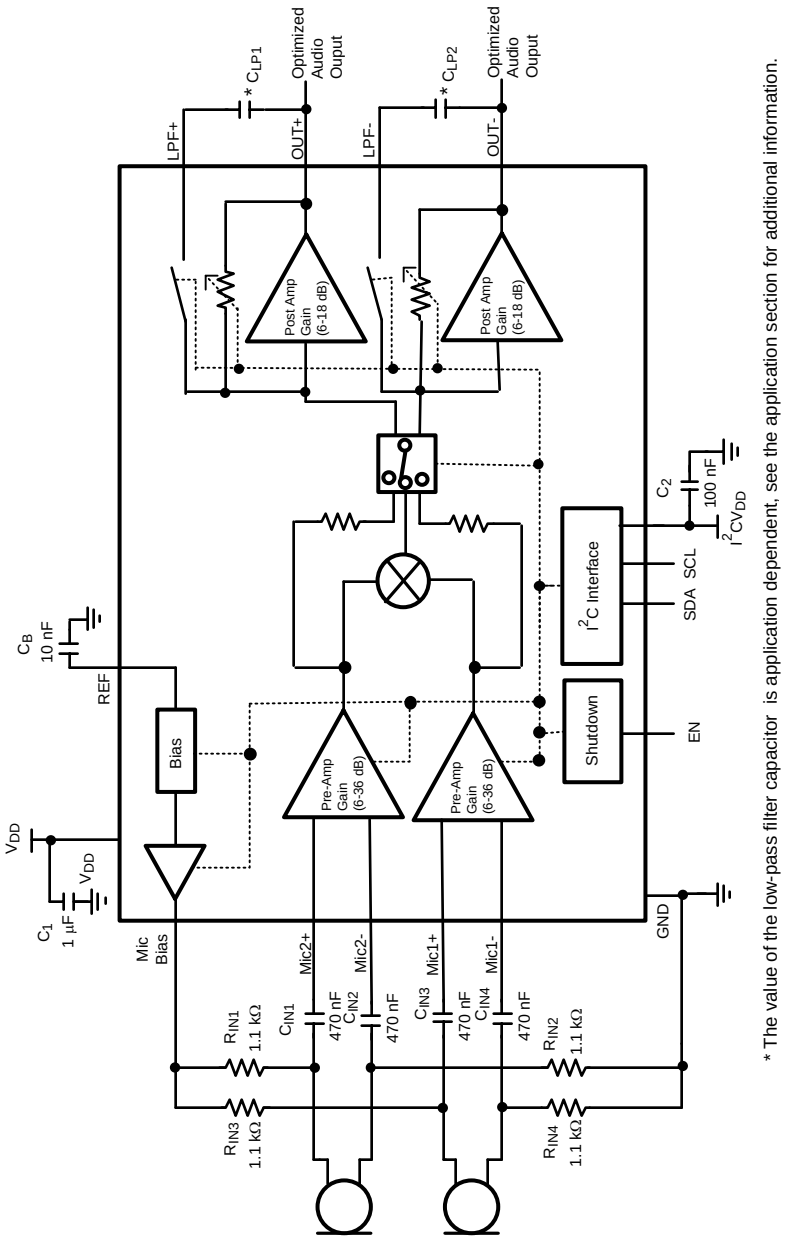

Figure 1. Typical Dual Microphone Far Field noise Cancelling Application

Connection Diagram

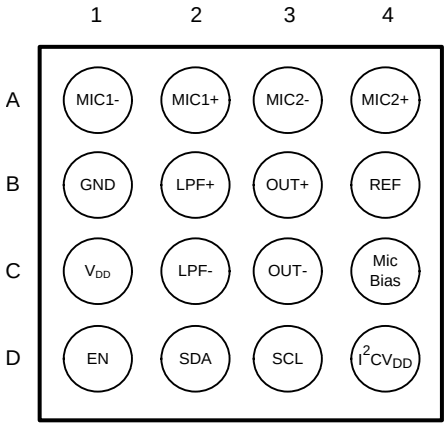

Figure 2. 16–Bump DSBGA (Top View)
See YZR0016 Package

PIN DESCRIPTIONS

Bump Number	Pin Name	Pin Function	Pin Type
A1	MIC1–	Microphone 1 negative input	Analog Input
A2	MIC1+	Microphone 1 positive input	Analog Input
A3	MIC2–	Microphone 2 negative input	Analog Input
A4	MIC2+	Microphone 2 positive input	Analog Input
B1	GND	Amplifier ground	Ground
B2	LPF+	Low Pass Filter for positive output	Analog Input
B3	OUT+	Positive optimized audio output	Analog Output
B4	REF	Reference voltage de-coupling	Analog Reference
C1	V_{DD}	Power supply	Supply
C2	LPF-	Low Pass Filter for negative output	Analog Input
C3	OUT-	Negative optimized audio output	Analog Output
C4	Mic Bias	Microphone Bias	Analog Output
D1	EN	Chip enable	Digital input
D2	SDA	I^2C data	Digital Input/Output
D3	SCL	I^2C clock	Digital Input
D4	I^2CV_{DD}	I^2C power supply	Supply

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings[1][2]

Supply Voltage		6.0V
Storage Temperature		-85°C to +150°C
Power Dissipation[3]		Internally Limited
ESD Rating[4]		2000V
ESD Rating[5]		200V
CDM		500V
Junction Temperature (T_{JMAX})		150°C
Mounting Temperature	Infrared or Convection (20 sec.)	235°C
Thermal Resistance	θ_{JA} (DSBGA)	70°C/W
Soldering Information See AN-1112 "microSMD Wafers Level Chip Scale Package."		

(1) "*Absolute Maximum Ratings*" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the *Absolute Maximum* Ratings or other conditions beyond those indicated in the *Recommended Operating Conditions* is not implied. The *Recommended Operating Conditions* indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
(3) The maximum power dissipation must be de-rated at elevated temperatures and is dictated by T_{JMAX}, θ_{JC}, and the ambient temperature T_A. The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA}$ or the number given in the *Absolute Maximum Ratings*, whichever is lower. For the LMV1090, T_{JMAX} = 150°C and the typical θ_{JA} for this DSBGA package is 70°C/W. Refer to the Thermal Considerations section for more information.
(4) Human body model, applicable std. JESD22-A114C.
(5) Machine model, applicable std. JESD22-A115-A.

Operating Ratings[1]

Supply Voltage	$2.7V \le V_{DD} \le 5.5V$
I^2CV_{DD} Supply Voltage[2]	$1.7V \le I^2CV_{DD} \le 5.5V$
$T_{MIN} \le T_A \le T_{MAX}$	$-40°C \le T_A \le +85°C$

(1) "*Absolute Maximum Ratings*" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the *Absolute Maximum* Ratings or other conditions beyond those indicated in the *Recommended Operating Conditions* is not implied. The *Recommended Operating Conditions* indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
(2) The voltage at I^2CV_{DD} must not exceed the voltage on V_{DD}.

Electrical Characteristics 3.3V[1][2]

Unless otherwise specified, all limits specified for T_A = 25°C, V_{DD} = 3.3V, V_{IN} = 18mV_{P-P}, f = 1kHz, EN = V_{DD}, Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF, f = 1kHz pass through mode.

Symbol	Parameter	Conditions	LMV1090		Units (Limits)
			Typical[3]	Limit[4]	
SNR	Signal-to-Noise Ratio	V_{IN} = 18mV_{P-P} A-weighted, Audio band	63		dB
		V_{OUT} = 18V_{P-P}, voice band (300–3400Hz)	65		dB
e_N	Input Referred Noise level	A-Weighted	5		μV_{RMS}
V_{IN}	Maximum Input Signal	THD+N < 1%, Pre Amp Gain = 6dB	880	820	mV_{P-P} (min)

(1) "*Absolute Maximum Ratings*" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the *Absolute Maximum* Ratings or other conditions beyond those indicated in the *Recommended Operating Conditions* is not implied. The *Recommended Operating Conditions* indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
(2) *The Electrical Characteristics* tables list specified specifications under the listed *Recommended Operating Conditions* except as otherwise modified or specified by the *Electrical Characteristics Conditions* and/or Notes. Typical specifications are estimations only and are not ensured
(3) Typical values represent most likely parametric norms at T_A = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not ensured
(4) Datasheet min/max specification limits are ensured by test, or statistical analysis.

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Electrical Characteristics 3.3V[1][2] (continued)

Unless otherwise specified, all limits specified for T_A = 25°C, V_{DD} = 3.3V, V_{IN} = 18mV_{P-P}, f = 1kHz, EN = V_{DD}, Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF, f = 1kHz pass through mode.

Symbol	Parameter	Conditions	LMV1090		Units (Limits)
			Typical[3]	Limit[4]	
V_{OUT}	Maximum AC Output Voltage	Differential Out+, Out- THD+N < 1%	1.2	1.1	V_{RMS} (min)
	DC Level at Outputs	Out+, Out-	820		mV
THD+N	Total Harmonic Distortion + Noise	Differential Out+ and Out-	0.1	0.2	% (max)
Z_{IN}	Input Impedance		142		kΩ
Z_{OUT}	Output Impedance (Differential)		220		Ω
Z_{LOAD}	Load Impedance (Out+, Out-)[5]	R_{LOAD} C_{LOAD}		10 100	kΩ (min) pF (max)
A_M	Microphone Preamplifier Gain Range	minimum maximum	6 36		dB dB
A_{MR}	Microphone Preamplifier Gain Adjustment Resolution		2	1.7 2.3	dB (min) dB (max)
A_P	Post Amplifier Gain Range	minimum maximum	6 18		dB dB
A_{PR}	Post Amplifier Gain Resolution		3	2.6 3.4	dB (min) dB (max)
$FFNS_E$	Far Field Noise Suppression Electrical	f = 1kHz (See Test Methods) f = 300Hz (See Test Methods)	34 42	26	dB dB
$SNRI_E$	Signal-to-Noise Ratio Improvement Electrical	f = 1kHz (See Test Methods) f = 300Hz (See Test Methods)	26 33	18	dB dB
PSRR	Power Supply Rejection Ratio	Input Referred, Input AC grounded			
		f_{RIPPLE} = 217Hz (V_{RIPPLE} = 100mV_{P-P})	99	85	dB (min)
		f_{RIPPLE} = 1kHz (V_{RIPPLE} = 100mV_{P-P})	95	80	dB (min)
CMRR	Common Mode Rejection Ratio	input referred	60		dB
V_{BM}	Microphone Bias Supply Voltage	I_{BIAS} = 1.2mA	2.0	1.85 2.15	V (min) V (max)
e_{VBM}	Mic bias noise voltage on V_{REF} pin	A-Weighted, C_B = 10nF	7		μV_{RMS}
I_{DDQ}	Supply Quiescent Current	V_{IN} = 0V	0.60	0.80	mA (max)
I_{DD}	Supply Current	V_{IN} = 25mV_{P-P} both inputs Noise cancelling mode	0.60		mA
I_{SD}	Shut Down Current	EN pin = GND	0.1	0.7	μA (max)
$I_{DD}I^2C$	I^2C supply current	I^2C Idle Mode	25	100	nA (max)
T_{ON}	Turn-On Time[6]			40	ms (max)
T_{OFF}	Turn-Off Time[6]			60	ms (max)

(5) Ensured by design.
(6) Ensured by design.

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Electrical Characteristics 5.0V[1][2]

Unless otherwise specified, all limits ensured for T_A = 25°C, V_{DD} = 5V, V_{IN} = 18mV$_{P-P}$, EN = V_{DD}, Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF, f = 1kHz pass through mode.

Symbol	Parameter	Conditions	LMV1090		Units (Limits)
			Typical[3]	Limit[4]	
SNR	Signal-to-Noise Ratio	V_{IN} = 18mV$_{P-P}$ A-weighted, Audio band	63		dB
		V_{OUT} = 18mV$_{P-P}$, voice band (300–3400Hz)	65		dB
e_N	Input Referred Noise level	A-Weighted	5		μV$_{RMS}$
V_{IN}	Maximum Input Signal	THD+N < 1%	880	820	mV$_{P-P}$ (min)
V_{OUT}	Maximum AC Output Voltage	f = 1kHz, THD+N < 1% between differential output	1.2	1.1	V$_{RMS}$ (min)
	DC Output Voltage		820		mV
THD+N	Total Harmonic Distortion + Noise	Differential Out+ and Out-	0.1	0.2	% (max)
Z_{IN}	Input Impedance		142		kΩ
Z_{OUT}	Output Impedance		220		Ω
A_M	Microphone Preamplifier Gain Range	minimum maximum	6 36		dB dB
A_{MR}	Microphone Preamplifier Gain Adjustment Resolution		2	1.7 2.3	dB (min) dB (max)
A_P	Post Amplifier Gain Range	minimum maximum	6 18		dB dB
A_{PR}	Post Amplifier Gain Adjustment Resolution		3	2.6 3.4	dB (min) dB (max)
$FFNS_E$	Far Field Noise Suppression Electrical	f = 1kHz (See Test Methods) f = 300Hz (See Test Method)	34 42	26	dB dB
$SNRI_E$	Signal-to-Noise Ratio Improvement Electrical	f = 1kHz (See Test Methods) f = 300Hz (See Test Methods)	26 33	18	dB dB
PSRR	Power Supply Rejection Ratio	Input Referred, Input AC grounded			
		f_{RIPPLE} = 217Hz (V_{RIPPLE} = 100mV$_{P-P}$)	99	85	dB (min)
		f_{RIPPLE} = 1kHz (V_{RIPPLE} = 100mV$_{P-P}$)	95	80	dB (min)
CMRR	Common Mode Rejection Ratio	input referred	60		dB
V_{BM}	Microphone Bias Supply Voltage	I_{BIAS} = 1.2mA	2.0	1.85 2.15	V (min) V (max)
e_{VBM}	Microphone bias noise voltage on V_{REF} pin	A-Weighted, C_B = 10nF	7		μV$_{RMS}$
I_{DDQ}	Supply Quiescent Current	V_{IN} = 0V	0.60	0.80	mA (max)
I_{DD}	Supply Current	V_{IN} = 25mV$_{P-P}$ both inputs Noise cancelling mode	0.60		mA
I_{SD}	Shut Down Current	EN pin = GND	0.1		μA
$I_{DD}I^2C$	I^2C supply current	I^2C Idle Mode	25	100	nA (max)
T_{ON}	Turn On Time[5]			40	mA (max)
T_{OFF}	Turn Off Time[5]			60	ms (max)

(1) "*Absolute Maximum Ratings*" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the *Absolute Maximum* Ratings or other conditions beyond those indicated in the *Recommended Operating Conditions* is not implied. The *Recommended Operating Conditions* indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.
(2) The voltage at I^2C V_{DD} must not exceed the voltage on V_{DD}.
(3) Typical values represent most likely parametric norms at T_A = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not ensured
(4) Datasheet min/max specification limits are ensured by test, or statistical analysis.
(5) Ensured by design.

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Digital Interface Characteristics $I^2C_V_{DD}$ = 2.2V to 5.5V(1)(2)

The following specifications apply for V_{DD} = 5.0V and 3.3V, T_A = 25°C, 2.2V ≤ $I^2C_V_{DD}$ ≤ 5.5V, unless otherwise specified.

Symbol	Parameter	Conditions	LMV1090		Units (Limits)
			Typical(3)	Limits(4)(5)	
t_1	I^2C Clock Period			2.5	µs (min)
t_2	I^2C Data Setup Time			100	ns (min)
t_3	I^2C Data Stable Time			0	ns (min)
t_4	Start Condition Time			100	ns (min)
t_5	Stop Condition Time			100	ns (min)
t_6	I^2C Data Hold Time			100	ns (min)
V_{IH}	I^2C Input Voltage High	EN, SCL, SDA		$0.7xI^2CV_{DD}$	V (min)
V_{IL}	I^2C Input Voltage Low	EN, SCL, SDA		$0.3xI^2CV_{DD}$	V (max)

(1) *The Electrical Characteristics* tables list specified specifications under the listed *Recommended Operating Conditions* except as otherwise modified or specified by the *Electrical Characteristics Conditions* and/or Notes. Typical specifications are estimations only and are not ensured
(2) The voltage at I^2CV_{DD} must not exceed the voltage on V_{DD}.
(3) Human body model, applicable std. JESD22-A114C.
(4) Machine model, applicable std. JESD22-A115-A.
(5) Datasheet min/max specification limits are ensured by test, or statistical analysis.

Digital Interface Characteristics $I^2C_V_{DD}$ = 1.7V to 2.2V

The following specifications apply for V_{DD} = 5.0V and 3.3V, T_A = 25°C, 1.7V ≤ $I^2C_V_{DD}$ ≤ 2.2V, unless otherwise specified.

Symbol	Parameter	Conditions	LMV1090		Units (Limits)
			Typical(1)	Limits(2)	
t_1	I^2C Clock Period			2.5	µs (min)
t_2	I^2C Data Setup Time			250	ns (min)
t_3	I^2C Data Stable Time			0	ns (min)
t_4	Start Condition Time			250	ns (min)
t_5	Stop Condition Time			250	ns (min)
t_6	I^2C Data Hold Time			250	ns (min)
V_{IH}	I^2C Input Voltage High	EN, SCL, SDA		$0.7xI^2CV_{DD}$	V (min)
V_{IL}	I^2C Input Voltage Low	EN, SCL, SDA		$0.3xI^2CV_{DD}$	V (max)

(1) Typical values represent most likely parametric norms at T_A = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not ensured
(2) Datasheet min/max specification limits are ensured by test, or statistical analysis.

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Test Methods

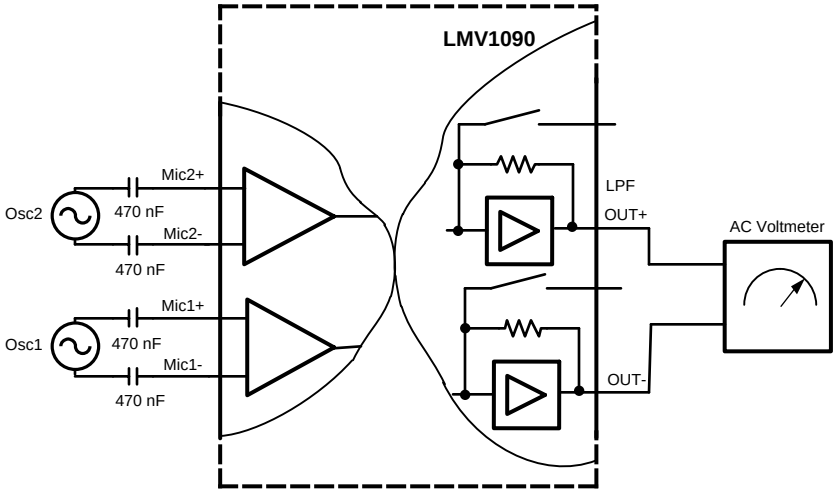

Figure 3. $FFNS_E$, $NFSL_E$, $SNRI_E$ Test Circuit

FAR FIELD NOISE SUPPRESSION ($FFNS_E$)

For optimum noise suppression the far field noise should be in a broadside array configuration from the two microphones (see Figure 22). Which means the far field sound source is equidistance from the two microphones. This configuration allows the amplitude of the far field signal to be equal at the two microphone inputs, however a slight phase difference may still exist. To simulate a real world application a slight phase delay was added to the $FFNS_E$ test. The block diagram from Figure 17 is used with the following procedure to measure the $FFNS_E$.

1. A sine wave with equal frequency and amplitude ($25mV_{P-P}$) is applied to Mic1 and Mic2. Using a signal generator, the phase of Mic 2 is delayed by 1.1° when compared with Mic1.
2. Measure the output level in dBV (X)
3. Mute the signal from Mic2
4. Measure the output level in dBV (Y)
5. $FFNS_E$ = Y - X dB

NEAR FIELD SPEECH LOSS ($NFSL_E$)

For optimum near field speech preservation, the sound source should be in an endfire array configuration from the two microphones (see Figure 23). In this configuration the speech signal at the microphone closest to the sound source will have greater amplitude than the microphone further away. Additionally the signal at microphone further away will experience a phase lag when compared with the closer microphone. To simulate this, phase delay as well as amplitude shift was added to the $NFSL_E$ test. The schematic from Figure 17 is used with the following procedure to measure the $NFSL_E$.

1. A $25mV_{P-P}$ and $17.25mV_{P-P}$ ($0.69*25mV_{P-P}$) sine wave is applied to Mic1 and Mic2 respectively. Once again, a signal generator is used to delay the phase of Mic2 by 15.9° when compared with Mic1.
2. Measure the output level in dBV (X)
3. Mute the signal from Mic2
4. Measure the output level in dBV (Y)
5. $NFSL_E$ = Y - X dB

SIGNAL TO NOISE RATIO IMPROVEMENT ELECTRICAL ($SNRI_E$)

The $SNRI_E$ is the ratio of $FFNS_E$ to $NFSL_E$ and is defined as:

$$SNRI_E = FFNS_E - NFSL_E \quad (1)$$

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Typical Performance Characteristics

Unless otherwise specified, T_J = 25°C, V_{DD} = 3.3V, Input Voltage = 18mV_{P-P}, f =1 kHz, pass through mode (Note 8), Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF.

THD+N vs Frequency Mic1 = AC GND, Mic2 = 36mV_{P-P} Noise Canceling Mode

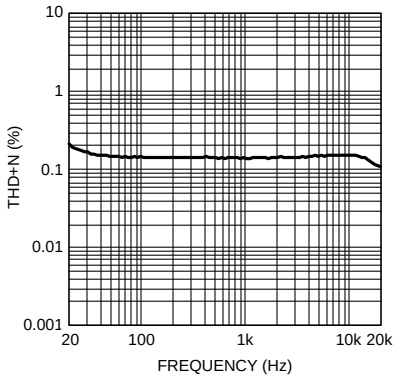

Figure 4.

THD+N vs Frequency Mic2 = AC GND, Mic1 = 36mV_{P-P} Noise Canceling Mode

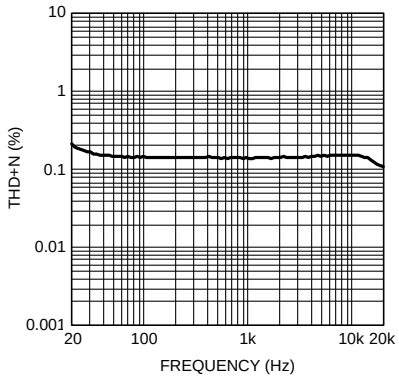

Figure 5.

THD+N vs Frequency Mic1 = 36mV_{P-P} Mic1 Pass Through Mode

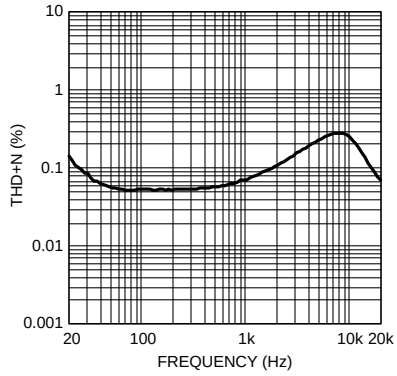

Figure 6.

THD+N vs Frequency Mic2 = 36mV_{P-P} Mic2 Pass Through Mode

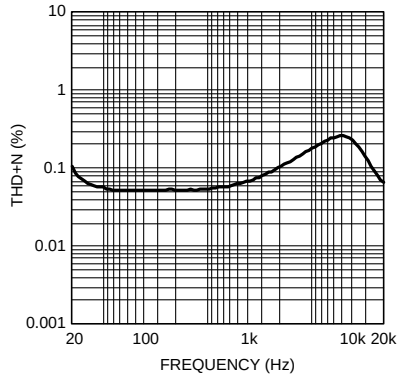

Figure 7.

THD+N vs Input Voltage Mic1 = AC GND, f = 1kHz Mic2 Noise Canceling Mode

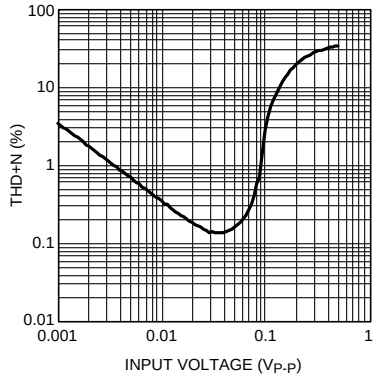

Figure 8.

THD+N vs Input Voltage Mic2 = AC GND, f = 1kHz Mic1 Noise Canceling Mode

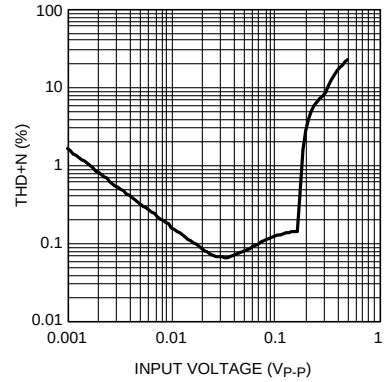

Figure 9.

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Typical Performance Characteristics (continued)

Unless otherwise specified, T_J = 25°C, V_{DD} = 3.3V, Input Voltage = 18mV_{P-P}, f =1 kHz, pass through mode (Note 8), Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF.

THD+N vs Input Voltage f = 1kHz Mic1 Pass Through Mode

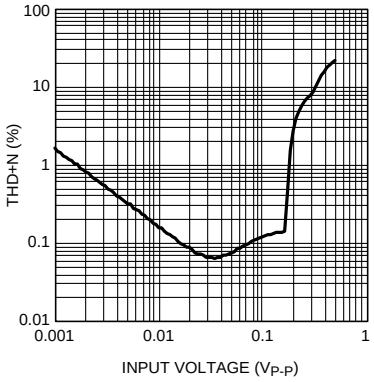

Figure 10.

THD+N vs Input Voltage f = 1kHz Mic2 Pass Through Mode

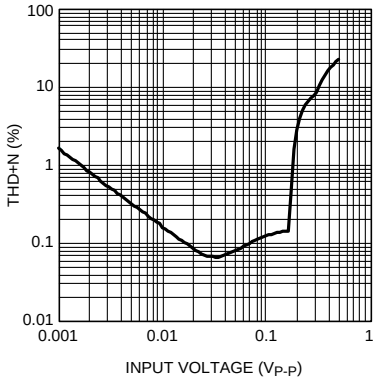

Figure 11.

PSRR vs Frequency Pre Amp Gain = 20dB, Post Amp Gain = 6dB V_{RIPPLE} = 100mV_{P-P}, Mic1 = Mic2 = AC GND Mic1 Pass Through Mode

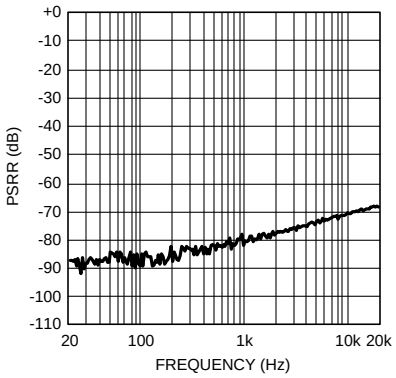

Figure 12.

PSRR vs Frequency Pre Amp Gain = 20dB, Post Amp Gain = 6dB V_{RIPPLE} = 100mV_{P-P}, Mic1 = Mic2 = AC GND Mic2 Pass Through Mode

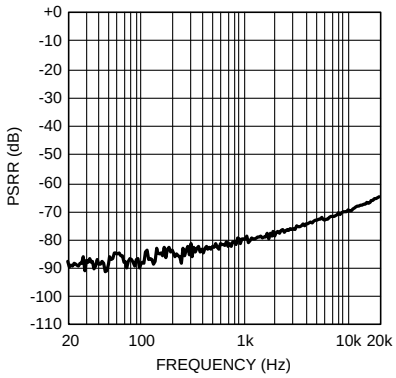

Figure 13.

PSRR vs Frequency Pre Amp Gain = 20dB, Post Amp Gain = 6dB V_{RIPPLE} = 100mV_{P-P}, Mic1 = Mic2 = AC GND Noise Canceling Mode

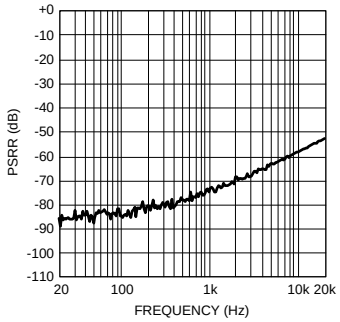

Figure 14.

Far Field Noise Suppression Electrical vs Frequency

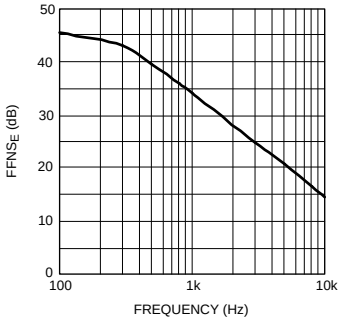

Figure 15.

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Typical Performance Characteristics (continued)

Unless otherwise specified, T_J = 25°C, V_{DD} = 3.3V, Input Voltage = 18mV_{P-P}, f =1 kHz, pass through mode (Note 8), Pre Amp gain = 20dB, Post Amp gain = 6dB, R_L = 100kΩ, and C_L = 4.7pF.

Signal-to-Noise Ratio Electrical vs Frequency

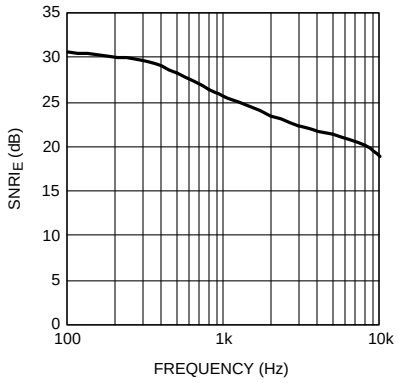

Figure 16.

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APPLICATION DATA

INTRODUCTION

The LMV1090 is a fully analog single chip solution to reduce the far field noise picked up by microphones in a communication system. A simplified block diagram is provided in Figure 17.

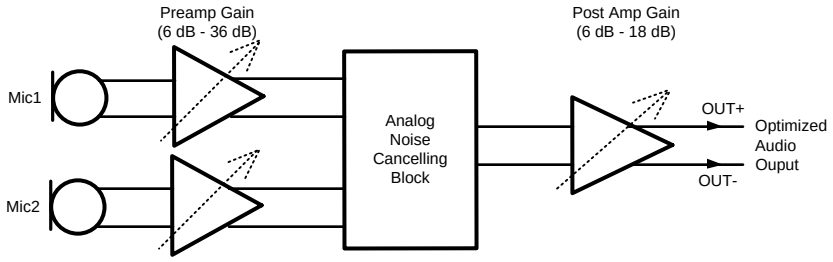

Figure 17. Simplified Block Diagram of the LMV1090

The output signal of the microphones is amplified by a pre-amplifier with adjustable gain between 6dB and 36dB. After the signals are matched the analog noise cancelling suppresses the far field noise signal. The output of the analog noise cancelling processor is amplified in the post amplifier with adjustable gain between 6dB and 18dB. For optimum noise and EMI immunity, the microphones have a differential connection to the LMV1090 and the output of the LMV1090 is also differential. The adjustable gain functions can be controlled via I^2C.

Power Supply Circuits

A low drop-out (LDO) voltage regulator in the LMV1090 allows the device to be independent of supply voltage variations.

The Power On Reset (POR) circuitry in the LMV1090 requires the supply voltage to rise from 0V to V_{DD} in less than 100ms.

The Mic Bias output is provided as a low noise supply source for the electret microphones. The noise voltage on the Mic Bias microphone supply output pin depends on the noise voltage on the internal the reference node. The de-coupling capacitor on the V_{REF} pin determines the noise voltage on this internal reference. This capacitor should be larger than 1nF; having a larger capacitor value will result in a lower noise voltage on the Mic Bias output.

Most of the logic levels for the digital control interface are relative to I^2CV_{DD} voltage. This eases interfacing to the micro controller of the application containing the LMV1090. The supply voltage on the I^2CV_{DD} pin must never exceed the voltage on the V_{DD} pin.

Only the four pins that determine the default power up gain have logic levels relative to V_{DD}.

Shutdown Function

As part of the Powerwise™ family, the LMV1090 consumes only 0.50mA of current. In many applications the part does not need to be continuously operational. To further reduce the power consumption in the inactive period, the LMV1090 provides two individual microphone power down functions. When either one of the shutdown functions is activated the part will go into shutdown mode consuming only a few µA of supply current.

SHUTDOWN VIA HARDWARE PIN

The hardware shutdown function is operated via the EN pin. In normal operation the EN pin must be at a 'high' level (V_{DD}). Whenever a 'low' level (GND) is applied to the EN pin the part will go into shutdown mode disabling all internal circuits.

Gain Balance and Gain Budget

In systems where input signals have a high dynamic range, critical noise levels or where the dynamic range of the output voltage is also limited, careful gain balancing is essential for the best performance. Too low of a gain setting in the preamplifier can result in higher noise levels while too high of a gain setting in the preamplifier will result in clipping and saturation in the noise cancelling processor and output stages.

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The gain ranges and maximum signal levels for the different functional blocks are shown in Figure 18. Two examples are given as a guideline on how to select proper gain settings.

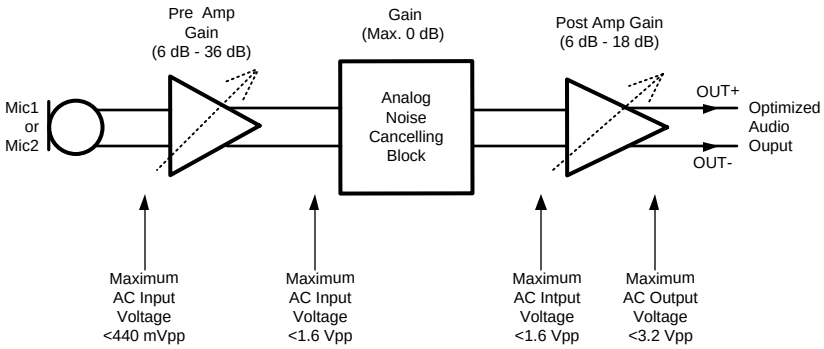

Figure 18. Maximum Signal Levels

Example 1

An application using microphones with $50mV_{P-P}$ maximum output voltage, and a baseband chip after the LMV1091 with $1.5V_{P-P}$ maximum input voltage.

For optimum noise performance, the gain of the input stage should be set to the maximum.

1. $50mV_{P-P}$ +36 dB = $3.1V_{P-P}$.
2. $3.1V_{P-P}$ is higher than the maximum $1.4V_{P-P}$ allowed for the Noise Cancelling Block (NCB). This means a gain lower than 29.5dB should be selected.
3. Select the nearest lower gain from the gain settings shown in Table 4, 28dB is selected. This will prevent the NCP from being overloaded by the microphone. With this setting, the resulting output level of the Pre Amplifier will be $1.26V_{P-P}$.
4. The NCB has a gain of 0dB which will result in $1.26V_{P-P}$ at the output of the LMV1091. This level is less than maximum level that is allowed at the input of the post amp of the LMV1091.
5. The baseband chip limits the maximum output voltage to $1.5V_{P-P}$ with the minimum of 6dB post amp gain, this results in requiring a lower level at the input of the post amp of $0.75V_{P-P}$. Now calculating this for a maximum preamp gain, the output of the preamp must be no more than $0.75V_{P-P}$.
6. Calculating the new gain for the preamp will result in <23.5dB gain.
7. The nearest lower gain will be 22dB.

So using preamp gain = 22dB and postamp gain = 6dB is the optimum for this application.

Example 2

An application using microphones with $10mV_{P-P}$ maximum output voltage, and a baseband chip after the LMV1090 with $3.3V_{P-P}$ maximum input voltage.

For optimum noise performance we would like to have the maximum gain at the input stage.

1. $10mV_{P-P}$ + 36dB = $631mV_{P-P}$.
2. This is lower than the maximum $1.5V_{P-P}$ so this is OK.
3. The NCB has a gain of 0dB which will result in $1.5V_{P-P}$ at the output of the LMV1091. This level is lower than maximum level that is allowed at the input of the Post Amp of the LMV1091.
4. With a Post Amp gain setting of 6dB the output of the Post Amp will be $3V_{P-P}$ which is OK for the baseband.
5. The nearest lower Post Amp gain will be 6dB.

So using preamp gain = 36dB and postamp gain = 6dB is optimum for this application.

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I²C Compatible Interface

The LMV1090 is controlled through an I²C compatible serial interface that consists of a serial data line (SDA) and a serial clock (SCL). The clock line are uni-directional. *The LMV1090 and the master can communicate at clock rates up to 400kHz. Figure 19 shows the I²C Interface timing diagram. Data on the SDA line must be stable during the HIGH period of SCL. The LMV1090 is a transmit/receive slave-only device, reliant upon the master to generate the SCL signal. Each transmission sequence is framed by a START condition and a STOP condition (Figure 20). The data line is 8 bits long and is always followed by an acknowledge pulse (Figure 21).

I²C Compatible Interface Power Supply Pin (I^2CV_{DD})

The LMV1090 I²C interface is powered up through the I^2CV_{DD} pin. The LMV1090 I²C interface operates at a voltage level set by the I^2CV_{DD} pin which can be set independent to that of the main power supply pin V_{DD}. This is ideal whenever logic levels for the I²C Interface are dictated by a microcontroller or microprocessor that is operating at a lower supply voltage than the main battery of a portable system.

I²C Bus Format

The I²C bus format is shown in Figure 21. The START signal, the transition of SDA from HIGH to LOW while SCL is HIGH is generated, alerting all devices on the bus that a device address is being written to the bus. The 7-bit device address is written to the bus, most significant bit (MSB) first followed by the R/W bit, R/W = 0 indicates the master is writing to the slave device, R/W = 1 indicates the master wants to read data from the slave device. Set R/W = 0; the LMV1090 is a WRITE-ONLY device and will not respond to the R/W = 1. The data is latched in on the rising edge of the clock. Each address bit must be stable while SCL is HIGH. After the last address bit is transmitted, the mater device release SDA, during which time, an acknowledge clock pulse is generated by the slave device. If the LMV1090 receives the correct address, the device pulls the SDA line low, generating an acknowledge bit (ACK)

Once the master device registers the ACK bit, the 8-bit register data word is sent. Each data bit should be stable while SCL is HIGH. After the 8-bit register data word is sent, the LMV1090 sends another ACK bit. Following the acknowledgement of the last register data word, the master issues a STOP bit, allowing SDA to go high while SCL is high.

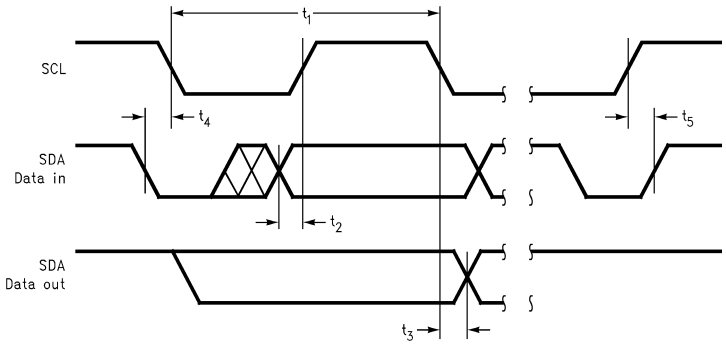

Figure 19. I²C Timing Diagram

*The data line is bi-directional (open drain)

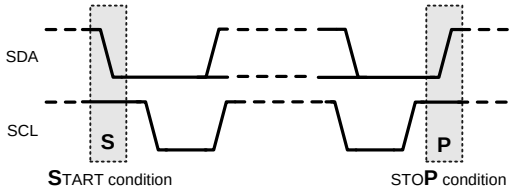

Figure 20. I²C Start Stop Conditions

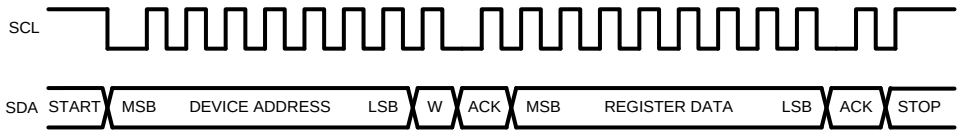

Figure 21. Start and Stop Diagram

Table 1. Chip Address

	B7	B6	B5	B4	B3	B2	B1	B0/$\overline{W}$
Chip Address	1	1	0	0	1	1	1	0

Table 2. I^2C Register Description

Address B[7]	Reg.	Bits	Description		Default
0	A	Gain setting for the pre amplifier from 6dB up to 36dB in 2dB steps			
		[3:0]	0000	6dB	0000
			0001	8dB	
			0010	10dB	
			0011	12dB	
			0100	14dB	
			0101	16dB	
			0110	18dB	
			0111	20dB	
			1000	22dB	
			1001	24dB	
			1010	26dB	
			1011	28dB	
			1100	30dB	
			1101	32dB	
			1110	34dB	
			1111	36dB	
		Gain setting for the post amplifier from 6dB to 18dB in 3dB steps			
		[6:4]	000	6dB	000
			001	9dB	
			010	12dB	
			011	15dB	
			100	18dB	
			101	18dB	
			110	18dB	
			111	18dB	
			111	18dB	

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Table 2. I²C Register Description (continued)

Address B[7]	Reg.	Bits	Description		Default
1	B	[1:0]	B[0] = mute mic 1 and B[1] = mute mic 2 (0 = microphone on)		00
		[3:2]	Mic enable bits, B[3] = enable Mic 2, B[2] = enable Mic 1 (1 = enable), B3 and B2 both 0 = disable Mic 1 and Mic 2		00
		Mic select bits			
		[5:4]	00	Noise cancelling mode	00
			01	Only Mic 1 enabled (pass through)	
			10	Only Mic 2 enabled (pass through)	
			11	Mic 1 + Mic 2	
		[6]	Not Used		

Microphone Placement

Because the LMV1090 is a microphone array Far Field Noise Reduction solution, proper microphone placement is critical for optimum performance. Two things need to be considered: The spacing between the two microphones and the position of the two microphones relative to near field source

If the spacing between the two microphones is too small near field speech will be canceled along with the far field noise. Conversely, if the spacing between the two microphones is large, the far field noise reduction performance will be degraded. The optimum spacing between Mic 1 and Mic 2 is 1.5-2.5cm. This range provides a balance of minimal near field speech loss and maximum far field noise reduction. The microphones should be in line with the desired sound source 'near speech' and configured in an endfire array (see Figure 23) orientation from the sound source. If the 'near speech' (desired sound source) is equidistant to the source like a broadside array (see Figure 22) the result will be a great deal of near field speech loss.

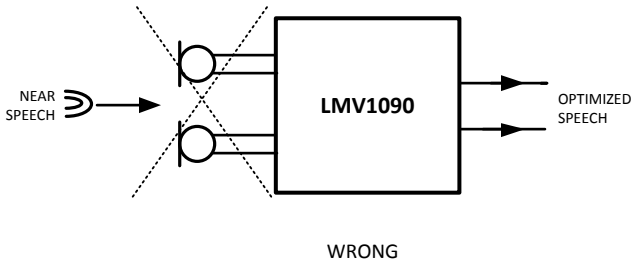

Figure 22. Broadside Array (WRONG)

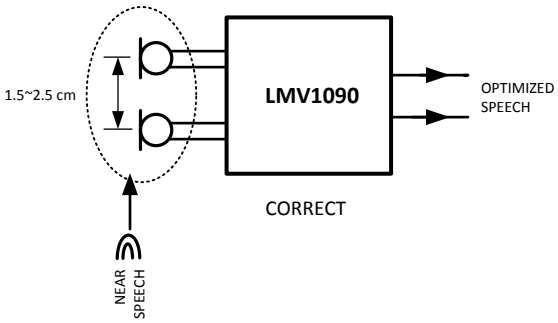

Figure 23. Endfire Array (CORRECT)

Low-Pass Filter At The Output

At the output of the LMV1090 there is a provision to create a 1st order low-pass filter (only enabled in 'Noise Cancelling' mode). This low-pass filter can be used to compensate for the change in frequency response that results from the noise cancellation process. The change in frequency response resembles a first-order high-pass filter, and for many of the applications it can be compensated by a first-order low-pass filter with cutoff frequency between 1.5kHz and 2.5kHz.

The transfer function of the low-pass filter is derived as:

$$H(s) = \frac{\text{Post Amplifier gain}}{sR_fC_f+1} \quad (2)$$

This low-pass filter is created by connecting a capacitor between the LPF pin and the OUT pin of the LMV1090. The value of this capacitor also depends on the selected output gain. For different gains the feedback resistance in the low-pass filter network changes as shown in Table 3.

This will result in the following values for a cutoff frequency of 2000 Hz:

Table 3. Low-Pass Filter Capacitor For 2kHz

Post Amplifier Gain Setting (dB)	R_f (kΩ)	C_f (nF)
6	20	3.9
9	29	2.7
12	40	2.0
15	57	1.3
18	80	1.0

A-Weighted Filter

The human ear is sensitive for acoustic signals within a frequency range from about 20Hz to 20kHz. Within this range the sensitivity of the human ear is not equal for each frequency. To approach the hearing response, weighting filters are introduced. One of those filters is the A-weighted filter.

The A-weighted filter is used in signal to noise measurements, where the wanted audio signal is compared to device noise and distortion.

The use of this filter improves the correlation of the measured values to the way these ratios are perceived by the human ear.

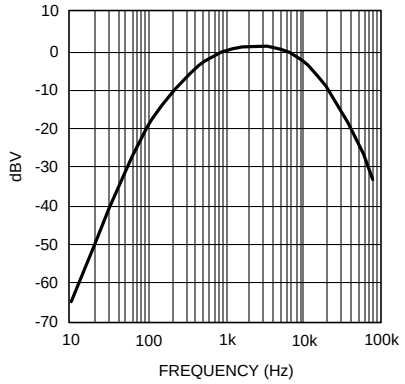

Figure 24. A-Weighted Filter

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Measuring Noise and SNR

The overall noise of the LMV1090 is measured within the frequency band from 10Hz to 22kHz using an A-weighted filter. The Mic+ and Mic- inputs of the LMV1090 are AC shorted between the input capacitors, see Figure 25.

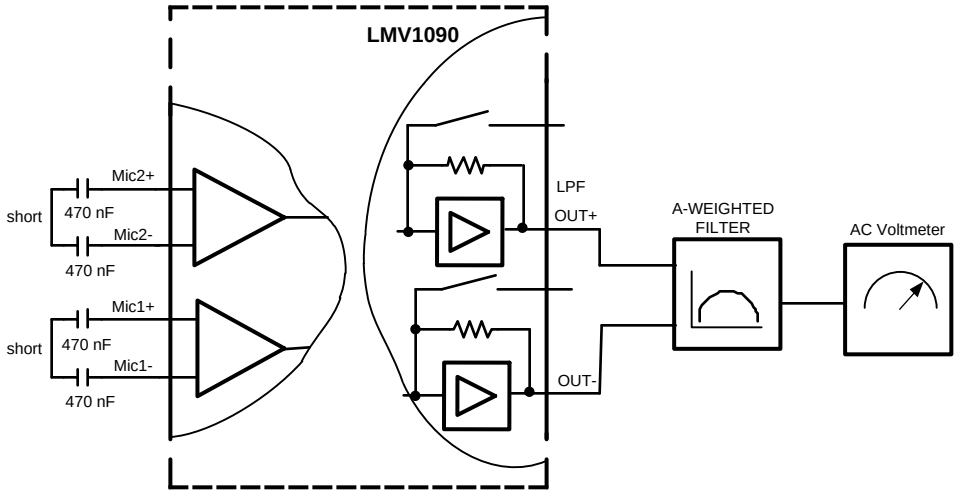

Figure 25. Noise Measurement Setup

For the signal to noise ratio (SNR) the signal level at the output is measured with a 1kHz input signal of $18mV_{P-P}$ using an A-weighted filter. This voltage represents the output voltage of a typical electret condenser microphone at a sound pressure level of 94dB SPL, which is the standard level for these measurements. The LMV1090 is programmed for 26dB of total gain (20dB preamplifier and 6dB postamplifier) with only Mic1 or Mic2 used. (See also I^2C Compatible Interface).

The input signal is applied differentially between the Mic+ and Mic-. Because the part is in Pass Through mode the low-pass filter at the output of the LMV1090 is disabled.

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Table 4. Revision History

Rev	Date	Description
1.0	07/01/09	Initial released.
1.01	07/10/09	Deleted the Limit values (on Zin) from both the 3.3V and 5V EC tables.
1.02	07/30/09	Edited the package dimensions (X1, X2, and X3).
1.03	09/02/09	Deleted the “Measurement Setup” paragraph.
1.04	10/12/09	Text edits.
1.05	10/15/09	Deleted the input limits on Zin (both from the 3.3V and 5.0V).
1.06	10/29/09	Text edits.
1.07	07/02/10	Edited curves 30083357 and 30083358.
I	05/02/13	Changed layout of National Data Sheet to TI format

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LMV1090TL/NOPB	NRND	DSBGA	YZR	16	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	ZA3	
LMV1090TLX/NOPB	NRND	DSBGA	YZR	16	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	ZA3	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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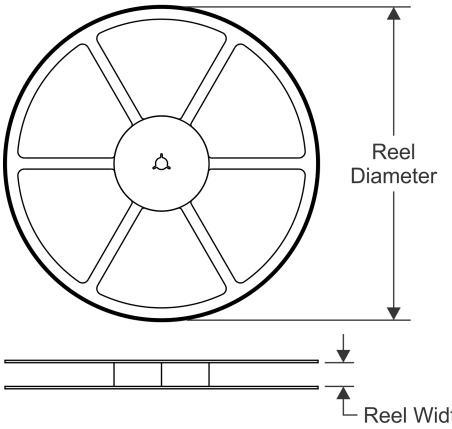
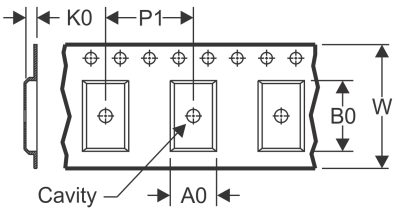
TAPE AND REEL INFORMATION

REEL DIMENSIONS

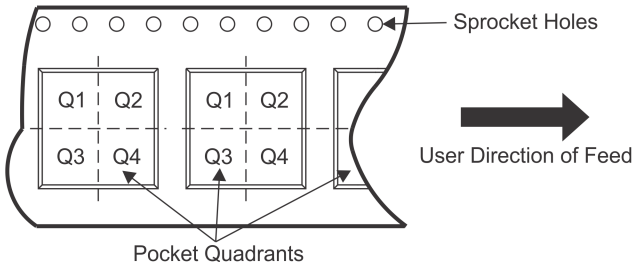


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

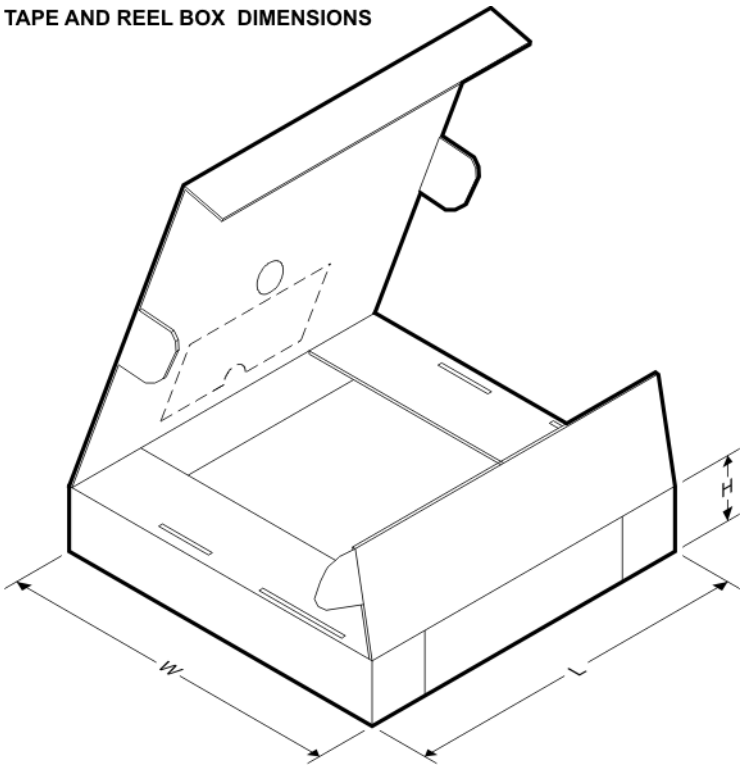
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV1090TL/NOPB	DSBGA	YZR	16	250	178.0	8.4	2.08	2.08	0.76	4.0	8.0	Q1
LMV1090TLX/NOPB	DSBGA	YZR	16	3000	178.0	8.4	2.08	2.08	0.76	4.0	8.0	Q1

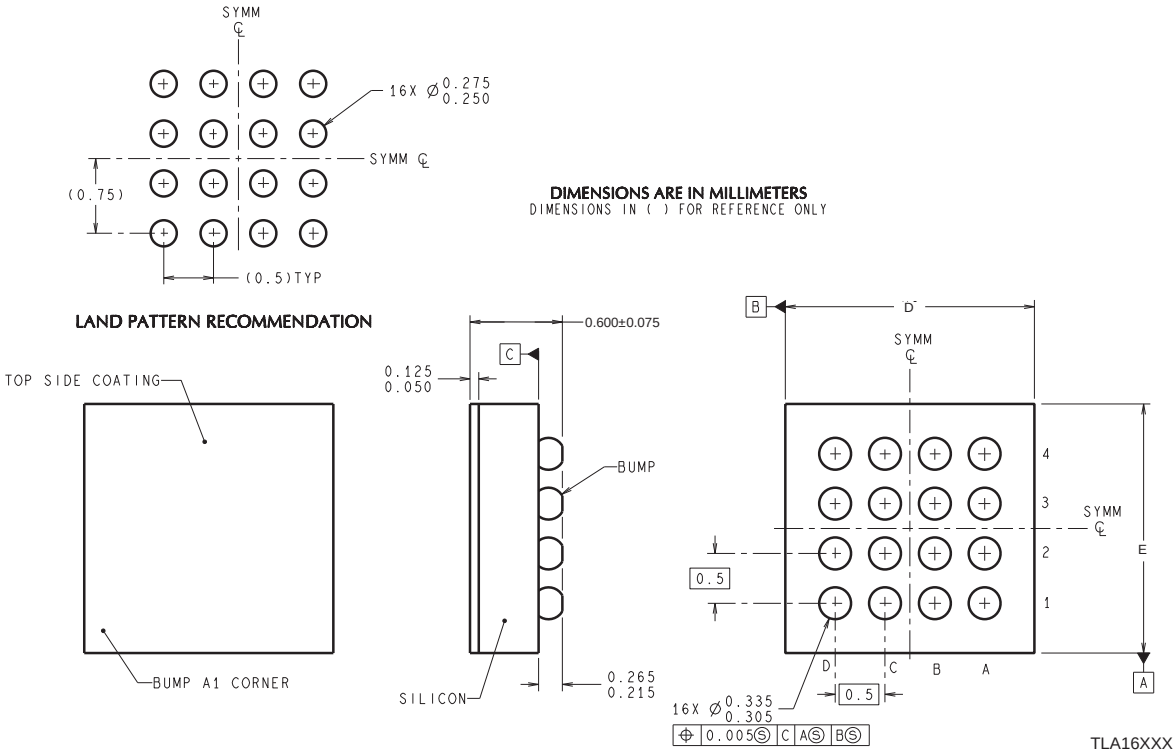
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV1090TL/NOPB	DSBGA	YZR	16	250	210.0	185.0	35.0
LMV1090TLX/NOPB	DSBGA	YZR	16	3000	210.0	185.0	35.0

YZR0016



D: Max = 1.991 mm, Min =1.931 mm

E: Max = 1.991 mm, Min =1.931 mm

4215051/A 12/12

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

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